# **BS108**

### **DMOS Transistors (N-Channel)**



Dimensions in inches and (millimeters)

### FEATURES

- High breakdown voltage
- High input impedance
- Low gate threshold voltage
  Low drain-source ON resistance
- High-speed switching
- No minority carrier storage time
- Kommonly camer storage time
   CMOS logic compatible input
- No thermal runaway
- No secondary breakdown
- Specially suited for telephone subsets
  - **MECHANICAL DATA**

**Case:** TO-92 Plastic Package **Weight:** approx. 0.18 g

On special request, this transistor is also manufactured in the pin configuration TO-18.

#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Value	Unit		
Drain-Source Voltage	V <sub>DSS</sub>	240	V		
Drain-Gate Voltage	V <sub>DGS</sub>	240	V		
Gate-Source Voltage (pulsed)	V <sub>GS</sub>	±20	V		
Drain Current (continuous)	ID	230	mA		
Power Dissipation at $T_{amb} = 25 \text{ °C}$	P <sub>tot</sub>	0.831)	W		
Junction Temperature	Tj	150	°C		
Storage Temperature Range	T <sub>S</sub>	-65 to +150	°C		
<sup>1)</sup> Valid provided that leads are kept at ambient temperature at a distance of 2 mm from case					

#### **Inverse Diode**

	Symbol	Value	Unit
Max. Forward Current (continuous) at T <sub>amb</sub> = 25 °C	lF	0.75	A
Forward Voltage Drop (typ.) at V <sub>GS</sub> = 0, I <sub>F</sub> = 0.75 A, T <sub>j</sub> = 25 °C	V <sub>F</sub>	0.85	V



# **BS108**

# ELECTRICAL CHARACTERISTICS Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage at $I_D = 100 \ \mu$ A, V <sub>GS</sub> = 0	V <sub>(BR)DSS</sub>	240	250	_	V
Gate-Body Leakage Current at $V_{GS}$ = 15 V, $V_{DS}$ = 0	I <sub>GSS</sub>	-	_	10	nA
Drain Cutoff Current at $V_{DS}$ = 130 V, $V_{GS}$ = 0 at $V_{DS}$ = 70 V, $V_{GS}$ = 0.2 V	I <sub>DSS</sub> I <sub>DSX</sub>	-		1 25	μΑ μΑ
Gate-Source Threshold Voltage at $V_{GS} = V_{DS}$ , $I_D = 1 \text{ mA}$	V <sub>GS(th)</sub>	0.8	1.5	2.5	V
Drain-Source ON Resistance at $V_{GS}$ = 2.8 V, I <sub>D</sub> = 100 mA	R <sub>DS(ON)</sub>	_	5.5	8	Ω
Thermal Resistance Junction to Ambient Air	R <sub>thJA</sub>	_	_	150 <sup>1)</sup>	K/W
Capacitance at $V_{DS} = 20 \text{ V}$ , $V_{GS} = 0$ , f = 1 MHz Input Capacitance Output Capacitance Feedback Capacitance	C <sub>iSS</sub> C <sub>OSS</sub> C <sub>rSS</sub>	- - -	80 20 5	- - -	pF pF pF
Switching Times at $V_{GS}$ = 10 V, $V_{DS}$ = 10 V, $R_D$ = 100 $\Omega$ Turn-On Time Turn-Off Time	t <sub>on</sub> t <sub>off</sub>	-	5 50	-	ns ns
<sup>1)</sup> Valid provided that leads are kept at ambient temperature at a distance of 2 mm from case					



### **RATINGS AND CHARACTERISTIC CURVES BS108**

Admissible power dissipation versus temperature Valid provided that leads are kept at ambient temperature at a distance of 2 mm from case



**Saturation characteristics** Pulse test width 80 ms; pulse duty factor 1%



BS108 Α 2.0 4.5  $T_{A} = 25$  C 1.6  $V_{GS} = 4 \text{ V}$ I<sub>D(ON)</sub> 1.2 3.5 0.8 3 2.5 0.4 2 1.5 0 0 20 40 60 80 100 V

**Output characteristics** Pulse test width 80 ms; pulse duty factor 1%

**Drain-source current** versus gate threshold voltage

→ V<sub>DS</sub>



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### **RATINGS AND CHARACTERISTIC CURVES BS108**

Drain current versus gate-source voltage Pulse test width 80 ms; pulse duty factor 1%



Normalized drain-source current versus temperature





Normalized gate-source voltage versus temperature

Normalized drain-source resistance versus temperature



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### **RATINGS AND CHARACTERISTIC CURVES BS108**

Drain-source resistance versus gate-source voltage



Transconductance versus gate-source voltage Pulse test width 80 ms; pulse duty factor 1%



Transconductance versus drain current

Pulse test width 80 ms; pulse duty factor 1%



